

Solder Materials

CORED WIRE

Product Name	Description	Key Attributes	Approximate Flux Content (% by Weight)	Diameter Range (mm)	Pb-Free Alloy	SnPb Alloy	IPC J-STE-004B Classification
Halogen-Free, No-Clean							
LOCTITE C 400	Cored solder wire	<ul style="list-style-type: none"> • Clear residue • Increased flux content for improved wetting on challenging surfaces • Award-winning multiple flux core technology that ensures consistent distribution of flux throughout the solder wire • Suitable for manual and robotic soldering 	2.2	0.38 – 1.63	<ul style="list-style-type: none"> • 90iSC • 99C • SAC305 • SAC387 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ROLO
Halide-Free, No-Clean							
LOCTITE C 502	Cored solder wire	<ul style="list-style-type: none"> • Clear residue • Good wetting on difficult substrates • Medium activity flux 	2.7	0.25 – 1.63	<ul style="list-style-type: none"> • SAC387 • SAC305 • 99C 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ROM1
LOCTITE C 511	Cored solder wire	<ul style="list-style-type: none"> • Amber residue • Good wetting on difficult substrates • Heat stable • Medium activity flux 	2.7	0.38 – 1.63	<ul style="list-style-type: none"> • SAC387 • SAC305 • 99C 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ROM1
Halide-Containing, Water Wash							
LOCTITE HYDX	Cored solder wire	<ul style="list-style-type: none"> • High activity flux • Excellent wetting on difficult substrates 	2.0	0.38 – 1.63	<ul style="list-style-type: none"> • 99C • SAC305 • SAC387 	<ul style="list-style-type: none"> • Sn60 • Sn62 • Sn63 	ORH1

SOLDER PASTE

Product Name	Description	Key Attributes	Alloy	Particle Size Distribution	IPC J-STE-004B Classification	Optimal Shelf Life	Reflow Atmosphere
Temperature Stable, Halogen-Free, No-Clean							
LOCTITE GC 10	Pb-free, solder paste	<ul style="list-style-type: none"> • RoHS-compliant • Excellent resistance to high humidity • Industry leader in paste transfer efficiency • Improved stability at different storage and operating temperatures • Extended stencil life up to 72 hr. • Extended abandon time up to 24 hr. • Suitable for high-density, small to large boards 	<ul style="list-style-type: none"> • SAC305 	<ul style="list-style-type: none"> • Type 3 • Type 4 • Type 4.5 (4A) • Type 5 	ROLO	1 year at 26.5 °C	Designed for air; suitable with nitrogen
Halogen-Free, No-Clean							
LOCTITE HF 212	Pb-free, solder paste	<ul style="list-style-type: none"> • High tack • Low voiding • RoHS-compliant • Excellent fine pitch coalescence • Designed for medium to large boards 	<ul style="list-style-type: none"> • 90iSC • SAC0307 • SAC305 • SAC387 	<ul style="list-style-type: none"> • Type 3 • Type 4 • Type 4.5 (4A) • Type 5 	ROLO	6 months at 0 °C – 10 °C	Air and nitrogen

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LIQUID FLUX

Product Name	Description	Key Attributes	Solid Content (% by Weight)	Acid Value (mg KOH/g)	Application	IPC J-STE-004B Classification
Halide-Containing, Water Wash						
LOCTITE HYDX-20	Liquid Flux	<ul style="list-style-type: none"> Highly water soluble Residues designed to be cleaned with deionized water Solders onto copper, brass, nickel and mild steel efficiently Compatible with Pb-free and SnPb wave solder processes 	20	24	Spray/Foam	ORH1
Halide-Free, No-Clean						
LOCTITE MF 210	Liquid flux	<ul style="list-style-type: none"> Resin-free flux designed to solder onto surfaces known to have poor solderability Recommended for applications where high throughput is required Compatible with Pb-free and SnPb wave solder processes 	2.9	22.5	Spray/Foam	ORMO
LOCTITE MF R301	Liquid flux	<ul style="list-style-type: none"> Higher solids flux for better wetting on surfaces known to have reduced solderability Minimizes bridging on complex geometries Fully Pb-free and dual wave compatible Solvent-based flux may be thinned with isopropyl alcohol (IPA) Compatible with Pb-free and SnPb wave solder processes 	6.0	40	Spray/Foam	ROMO
Halogen-Free, VOC-Free, No-Clean						
LOCTITE MF 300	Liquid flux	<ul style="list-style-type: none"> General-purpose, resin-free, water-based flux with special formulation designed to minimize solder balling Compatible with Pb-free and SnPb wave solder processes 	4.6	37	Spray/Foam	ORMO
Halogen-Free, No-Clean						
LOCTITE MF 390HR	Liquid flux	<ul style="list-style-type: none"> Exceptional through-hole fill Recommended for automotive applications and general electrical soldering applications Compatible with Pb-free and SnPb wave solder processes 	6.0	20 – 25	Spray/Foam	ROLO